

Intel® Server Board S2600CP4



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COMPATIBLE PRODUCTS

PRODUCT IMAGES

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SPECIFICATIONS

Essentials

Status	Launched
Launch Date	Q1'12
Limited 3-year Warranty	Yes
Extended Warranty Available for Purchase (Select Countries)	Yes
# of QPI Links	2
Board Form Factor	SSI EEB 12" x 13"
Chassis Form Factor	Pedestal
Socket	Socket R
Integrated Systems Available	Yes
Integrated BMC with IPMI	IPMI 2.0
Rack-Friendly Board	Yes
Embedded Options Available	Yes
Max TDP	135 W
Included Items	(1) Intel® Server Board S2600CP4. Also available in a 10-pack, 5-pack, or integrated in a system. The 5-pack also includes (5) DVDs and (5) Quick Start Guides.
Recommended Customer Price	N/A
Description	A mainstream server board supporting two Intel® Xeon® processor E5-2600, 16 DIMMs, four 1Gb Ethernet ports, six x8 electrical PCIe Gen3 IO slots, up to 8 SCU ports plus 2 SATA 6Gb ports and 4 SATA 3Gb ports with storage activation key.
Target Market	Small and Medium Business
Additional Information URL	Link

RELATED PRODUCTS

- Dual-Socket Server Boards
- Intel® Server Board S2600CP Family
- Products formerly Canoe Pass
- Intel® C602 Chipset

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QUICK LINKS

- No Datasheet Available
- [Export Full Specifications](#)
- [Additional Information](#)
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PCN/MDDS INFORMATION

916041: [PCN](#) | [MDDS](#)
 916042: [PCN](#) | [MDDS](#)

Memory Specifications

Max Memory Size (dependent on memory type)	512 GB
Reduced 1333 1333LV	
# of Memory Channels	8
Max Memory Bandwidth	119.5 GB/s
Physical Address Extensions	46-bit
# of DIMMs	16
ECC Memory Supported †	Yes

Graphics Specifications

Integrated Graphics †	Yes
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Graphics Output	15-pin VGA
Intel® Clear Video Technology	No
Discrete Graphics	Supported

Expansion Options

PCI Express Revision	3.0
Max # of PCI Express Lanes	48
PCIe x8 Gen 3	5
PCIe x16 Gen 3	1

I/O Specifications

USB Revision	2.0
# of USB Ports	5
USB 2.0 Configuration (Back + Internal)	4
Total # of SATA Ports	14
RAID Configuration	Up to SW Raid 5 (LSI + RSTe)
# of Serial Ports	2
# of LAN Ports	4
Integrated LAN	4x 1GbE
Firewire	No
Embedded USB (eUSB) Solid State Drive Option	Yes
Integrated SAS Ports	8
Integrated InfiniBand*	No

Package Specifications

Max CPU Configuration	2
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) †	Yes
Intel® vPro Technology †	No
Intel® ME Firmware Version	No
Intel® Remote Wake Technology	No
Intel® Remote PC Assist Technology	No
Intel® Remote Management Module Support	Yes
Intel® Node Manager	Yes
Intel® CIRA Technology	No
TPM Version	1.2
Intel® Quick Resume Technology	No
Intel® Quiet System Technology	No
Intel® HD Audio Technology	No
Intel® AC97 Technology	No
Intel® Matrix Storage Technology	No
Intel® Rapid Storage Technology	No
Intel® Rapid Storage Technology enterprise	Yes
Intel® Fast Memory Access	Yes
Intel® Flex Memory Access	Yes

<u>Intel® I/O Acceleration Technology</u>	Yes
<u>Intel® Advanced Management Technology</u>	Yes
<u>Intel® Server Customization Technology</u>	Yes
<u>Intel® Build Assurance Technology</u>	Yes
<u>Intel® Efficient Power Technology</u>	Yes
<u>Intel® Quiet Thermal Technology</u>	Yes
Intel® Data Protection Technology	
<u>AES New Instructions</u>	Yes
Intel® Platform Protection Technology	
<u>Trusted Execution Technology †</u>	Yes
<u>Anti-Theft Technology</u>	No

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"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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